



Vishay EFI Diced on Tape Guidelines

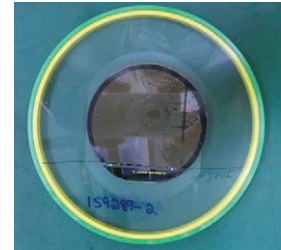
Vishay EFI part numbers with the pack code "ST" are sold as a full 3" or 5" wafers that have been diced into individual die. The parts are supplied as a sawn wafer on a tape ring (see picture below).



100 % Electrical Test



Dice Into Individual Die



Mounted Wafer to Ship

The individual die are 100 % electrically tested.

Vishay Electro-Films is not able to perform a 100 % visual inspection on products that are packaged and delivered "diced-on-tape". Therefore, the following conditions will apply to inspection on all orders:

- Parts will receive a sample visual inspection scan to ensure minimum yield requirements per wafer are met
- Vishay EFI will not guarantee that all product delivered is visually acceptable per military inspection standard, MIL-STD-883 method 2032, class H
- The diced-on-tape product will be 100 % electrically tested and electrical rejects will be marked by inking
- Any visual inspection rejects will not be inked. Vishay EFI will not be responsible for failures due to visual rejects

The number of die invoiced are the number of known good die which varies from wafer to wafer and part family to part family.

Using the MSFM family as an example, the minimum yield quantity is 12 000 pcs per wafer. So, we ask that customers order 12 000 pieces, guaranteeing that the customer will receive at least 12 000 good pieces with the chance of additional pieces.

STANDARD PART FAMILIES	
PART FAMILY	MINIMUM PIECES
MSFM	12 000
BCR	10 000

Please see the individual datasheets for more information. Or contact Vishay EFI directly at efi@vishay.com